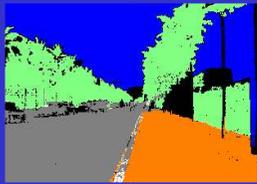


# Computer Vision and Robotics

Institut d'Informàtica i Aplicacions  
Universitat de Girona



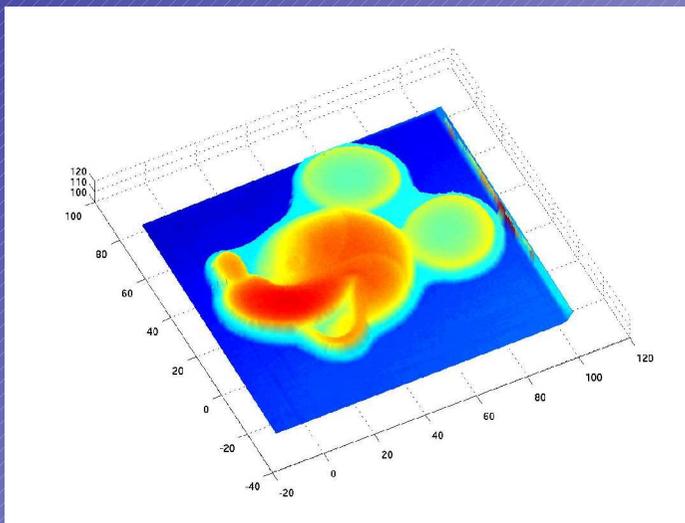
Underwater  
Robotics



Computer  
Vision

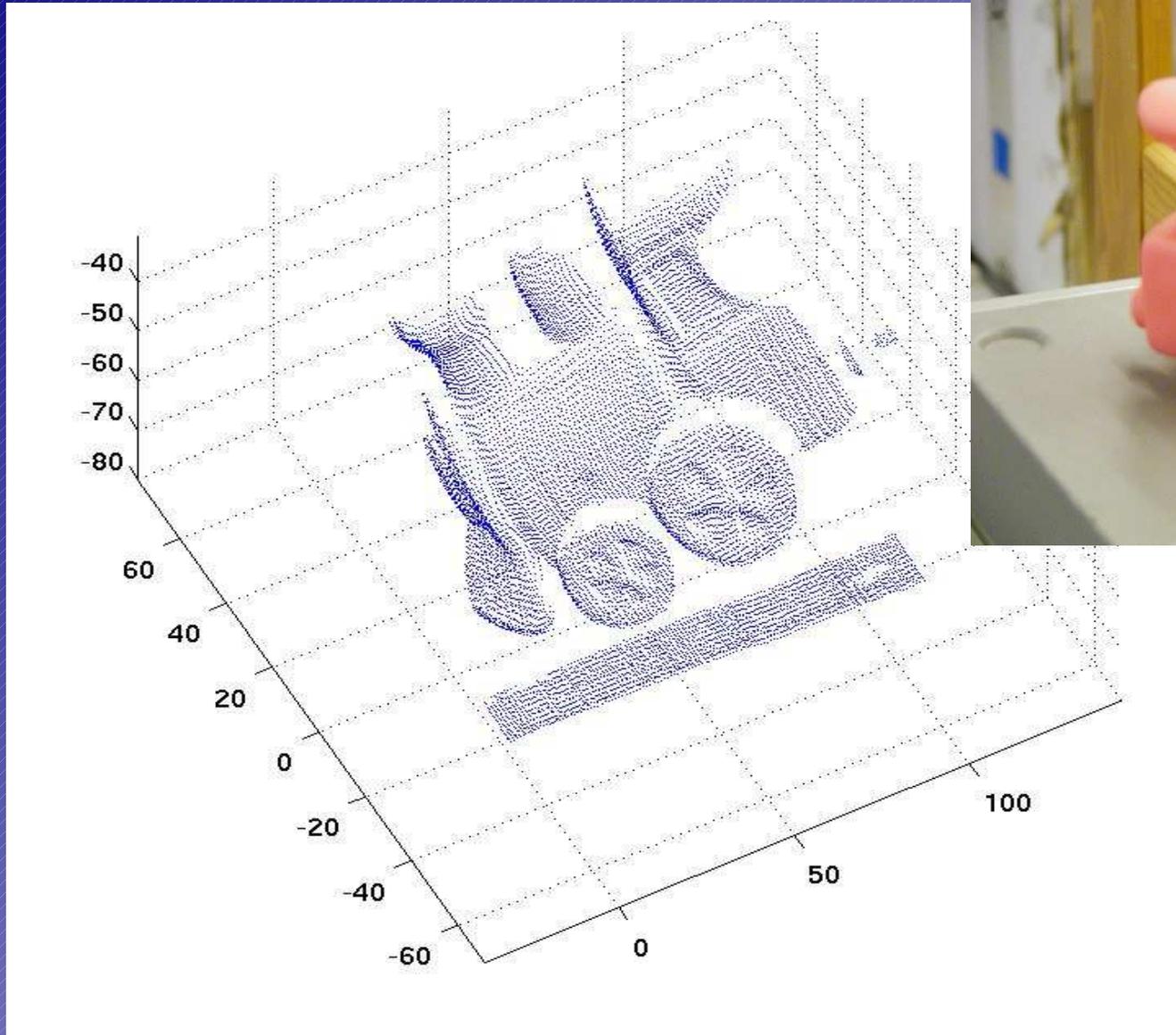


**Digital Hardware Architectures  
for real-time computer vision**



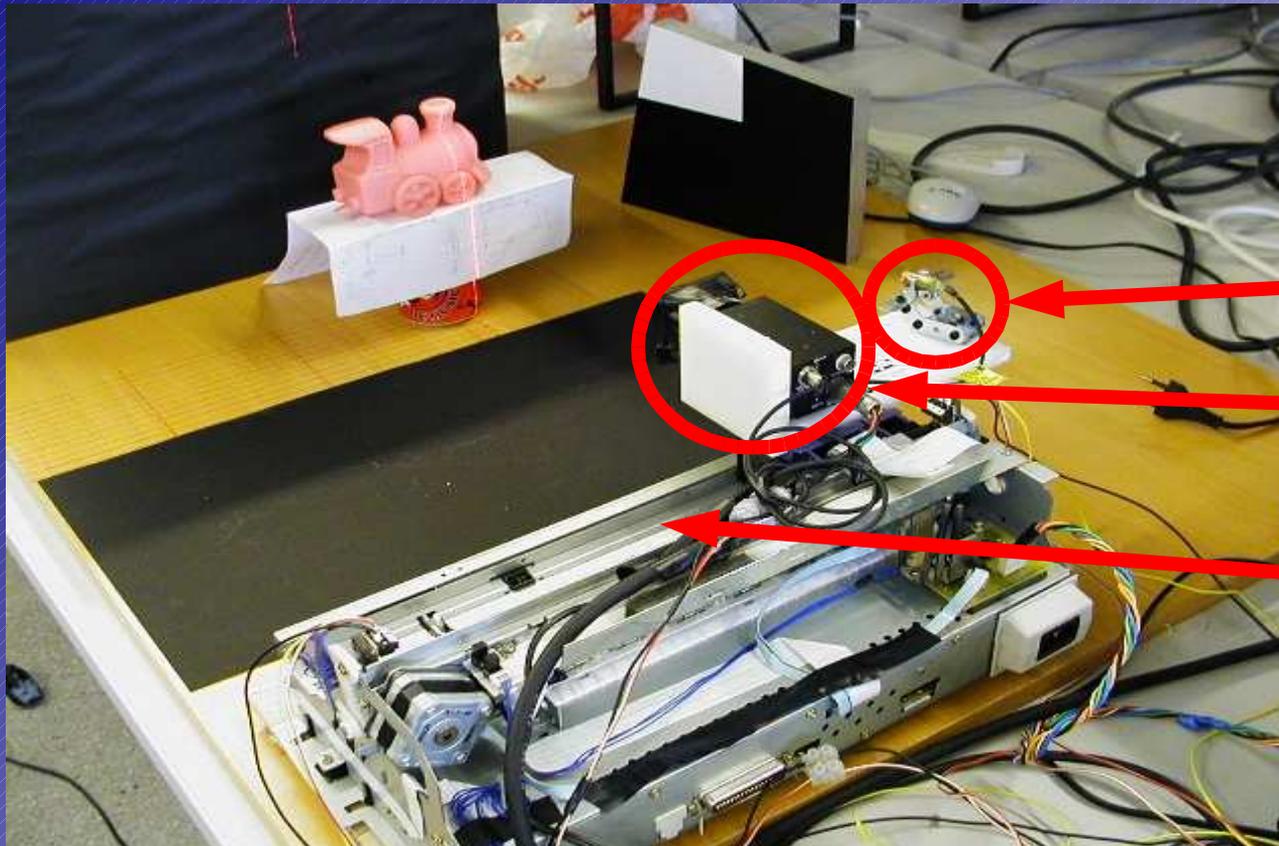
**Three-dimensional vision**

# Three-dimensional vision



# Three-dimensional vision

## 3D digitiser system



Laser Emitter

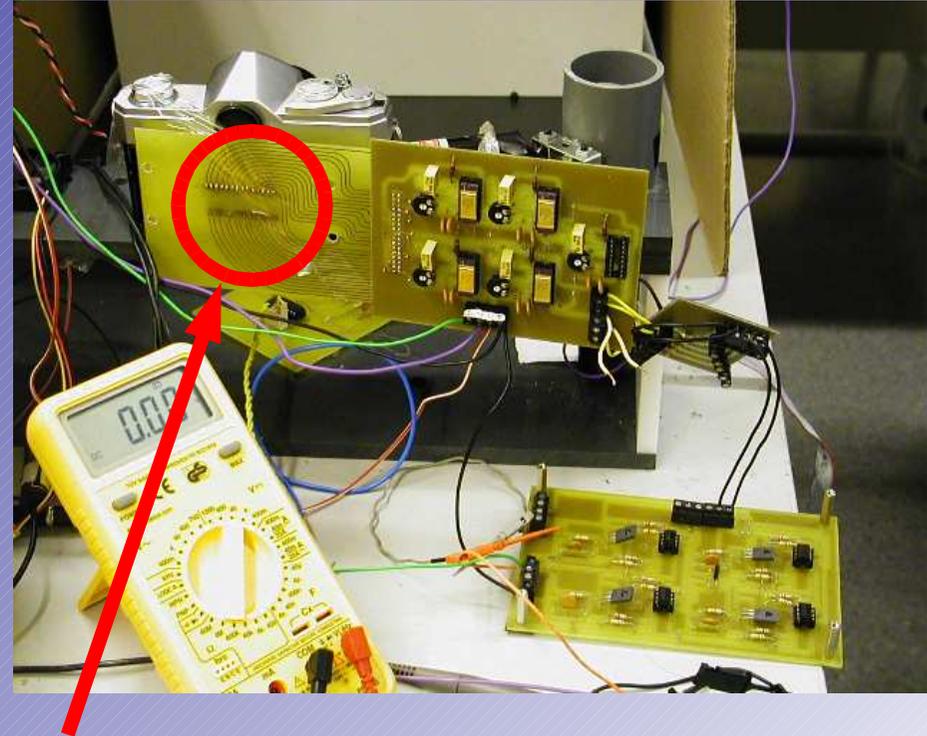
CCD camera

Motorised linear  
motion

Laser and camera scan the scene together. The linear motion is known to the system. The calibration and reconstruction by Projective Geometry principles (Chen & Kak, 1987).

# Three-dimensional vision

## Real-time Range finder

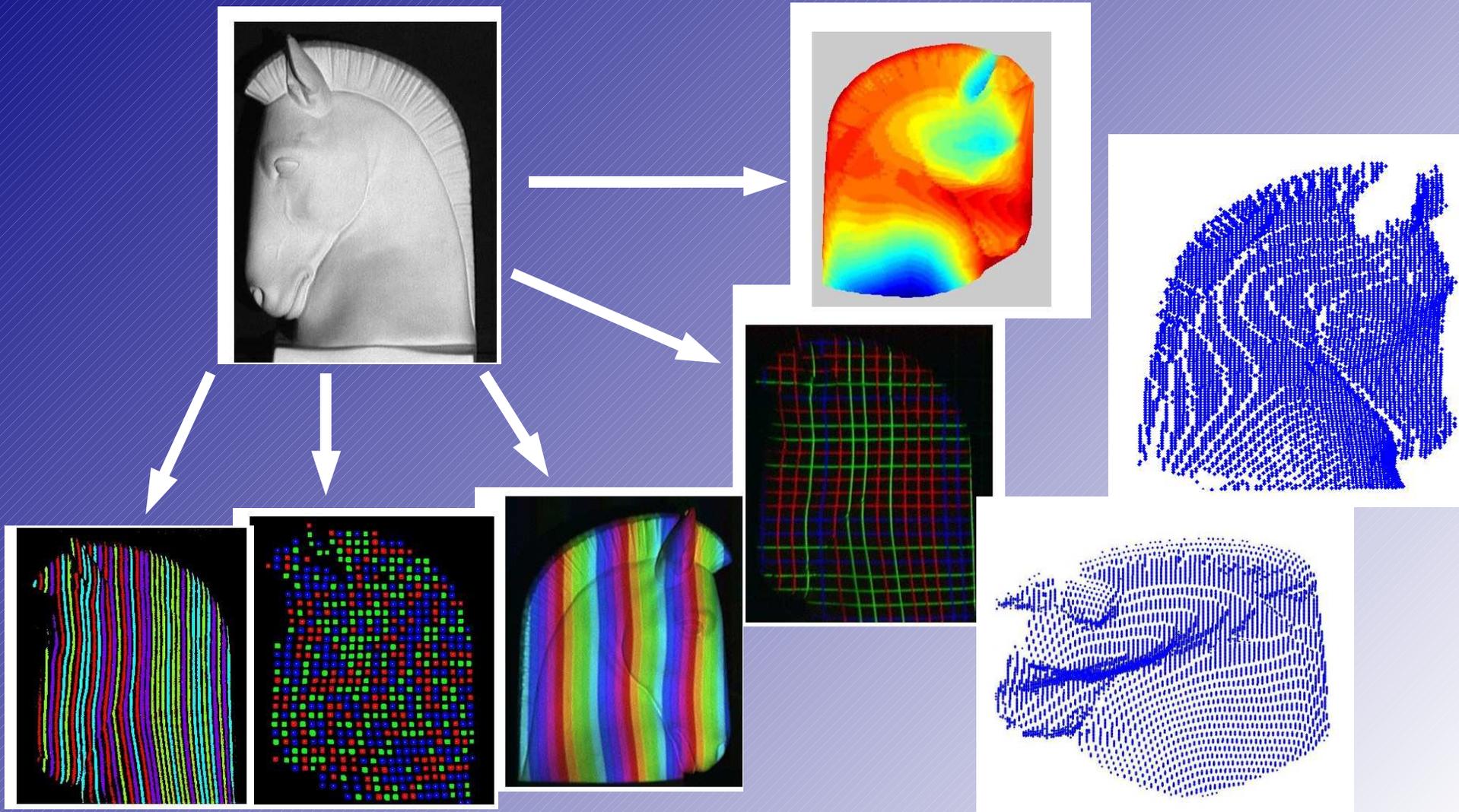


## 5x5 photodiodes sensor. Hamamatsu S7585

Constant speed laser rotation. The time between a known reference optical switch and the impact of the laser image between 2 consecutive PDs is measured (Yokoyama et. al. 1994).

# Three-dimensional vision

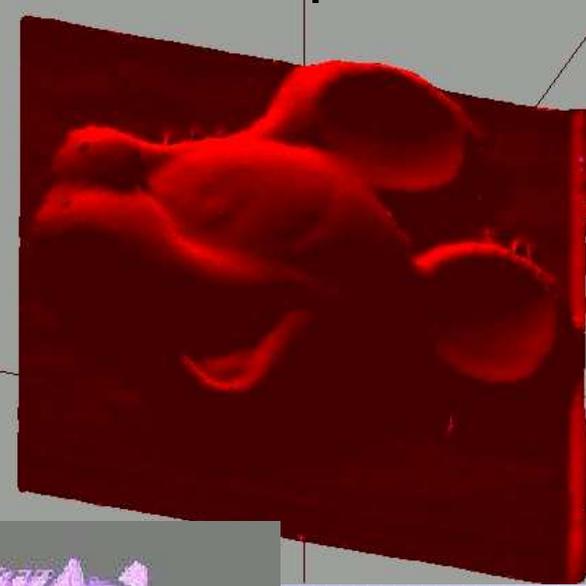
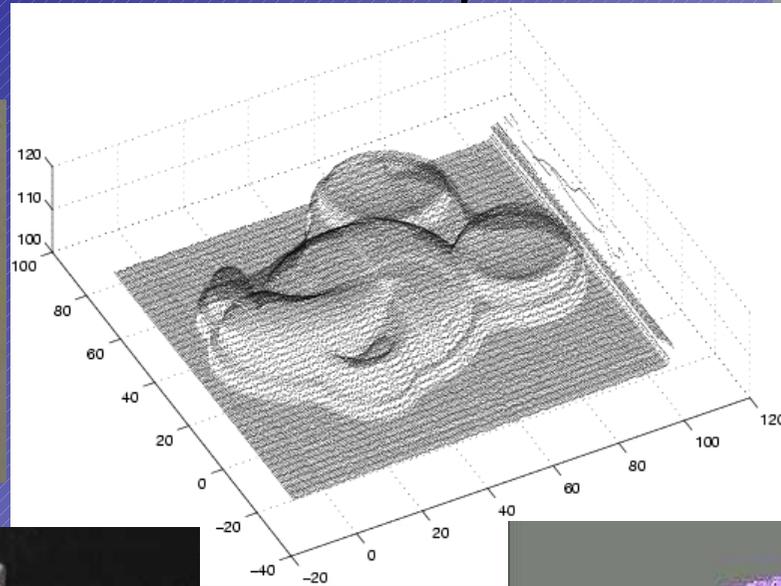
## Coded structured light pattern projection



# Three-dimensional vision

Cloud of points

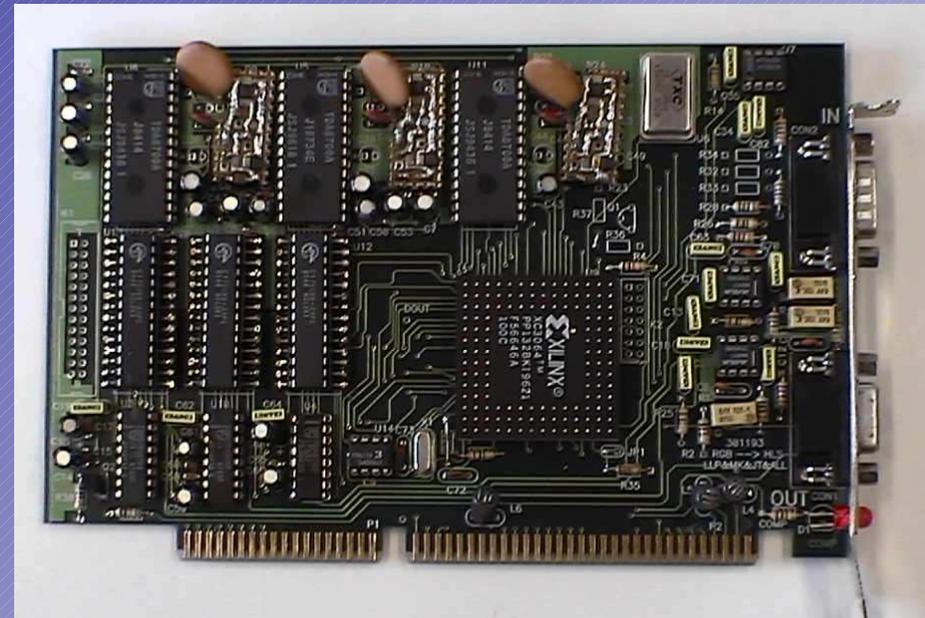
Surface interpolation



# Computer Vision Architectures

## RTC

1992. Video-rate segmentation of a scene by colour feature selection.



## MAGTRAK

1998. Video-rate multiple object tracking by using colour feature segmentation.

# Computer Vision Architectures

## MAGCL

2001. Modular distributed Architecture, allowing pipe-line and parallel interconnextino of different modules. Each module includes 1 FPGA and 1 DSP, which makes the most calculation-intensive tasks.



**MIRAGE.** 2002. 'Sandwich' type modular architecture. Additional boards may be added through 3 low-profile connectors.



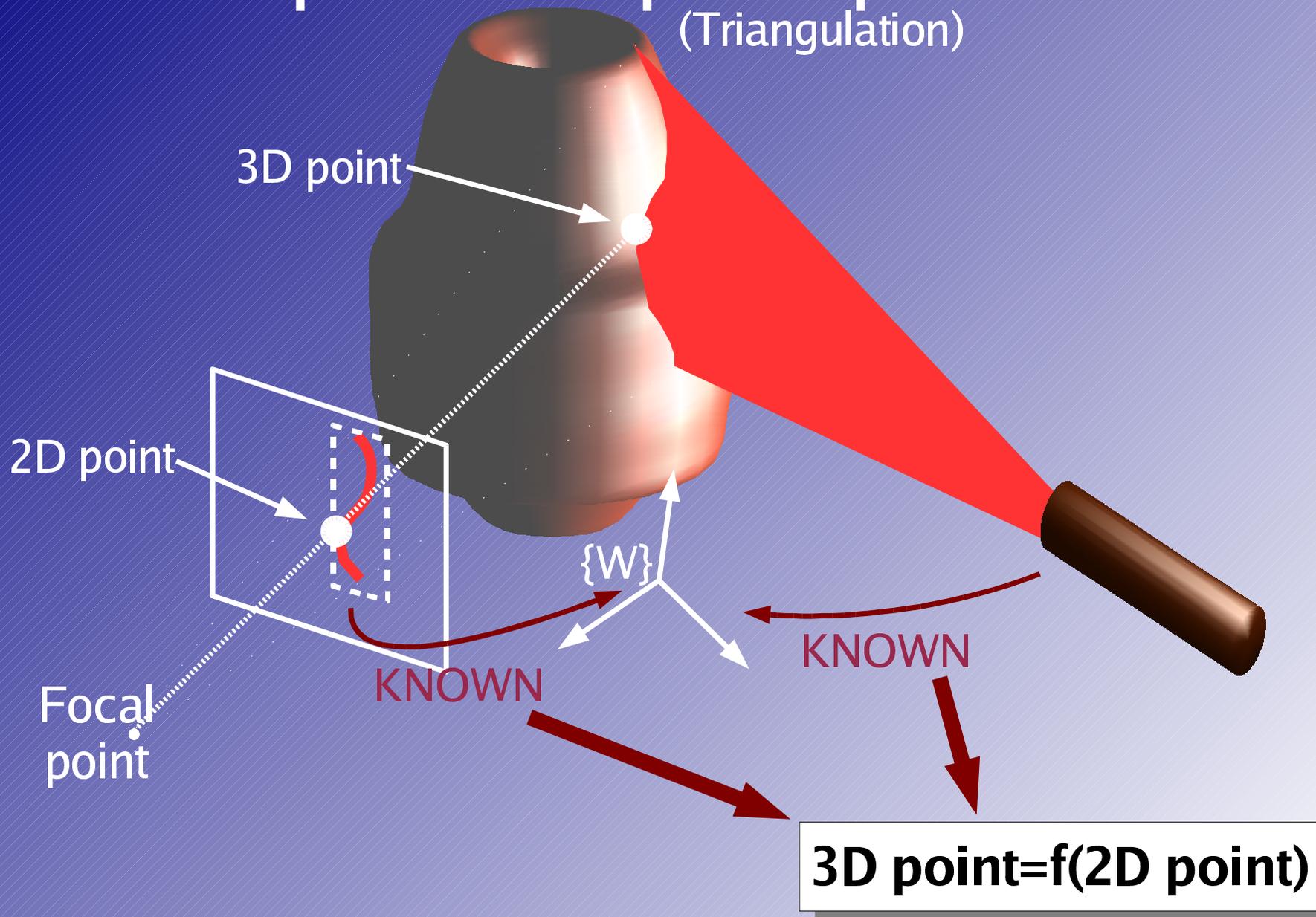
Allows the operation with 2 CVBS/RGB cameras and digital cameras. Implementation of a real-time 3D architecture.

A 30 Cloud-of-points per second  
three-dimensional digitiser:

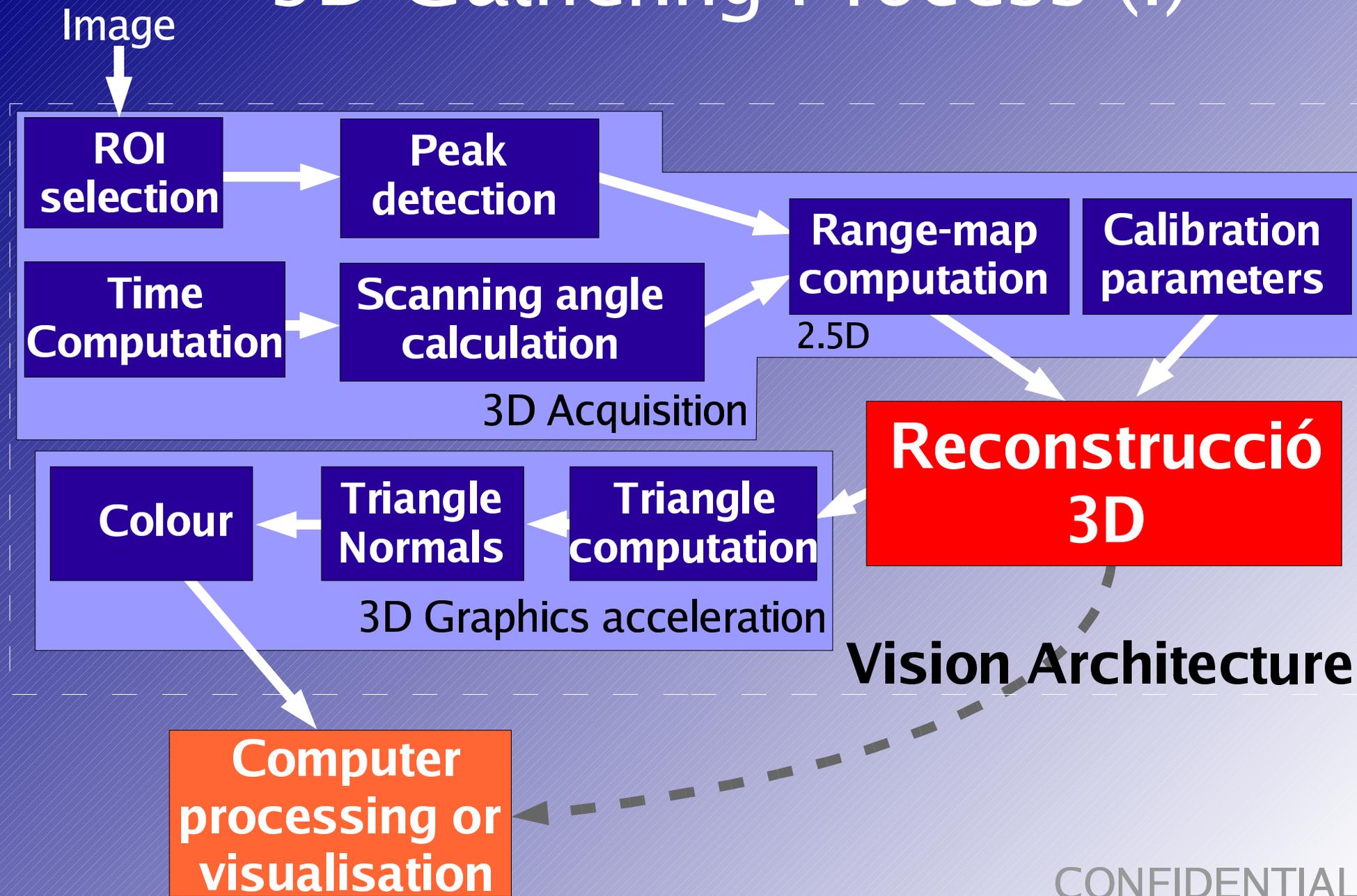
THE 3-DIMENSIONAL CAMERA

# Operation principle

(Triangulation)



# 3D Gathering Process (I)



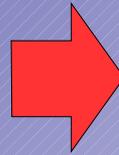
# 3D Gathering Process (II)

**3D Acquisition**



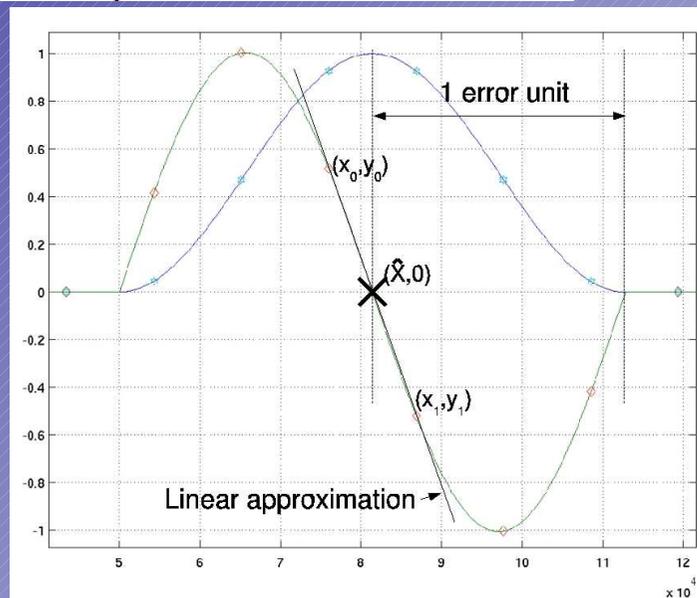
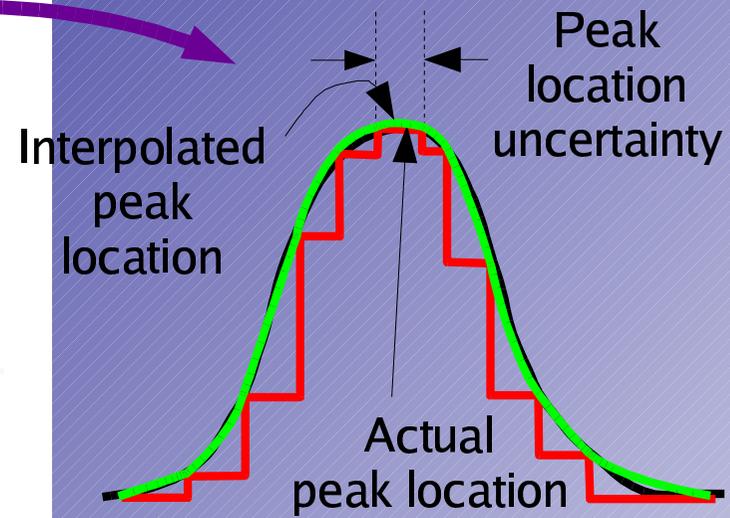
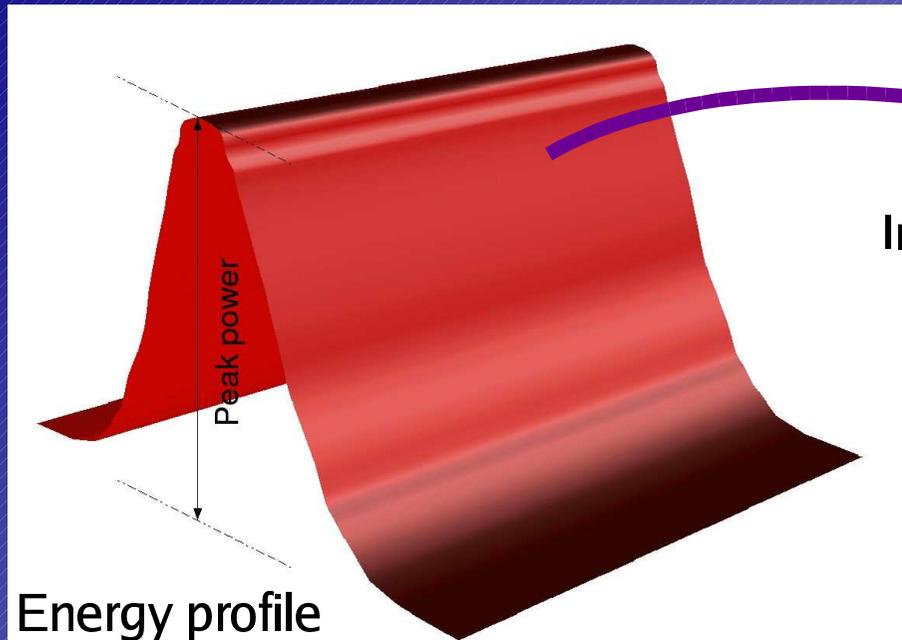
***High Speed  
High Accuracy***

**3D Acceleration**

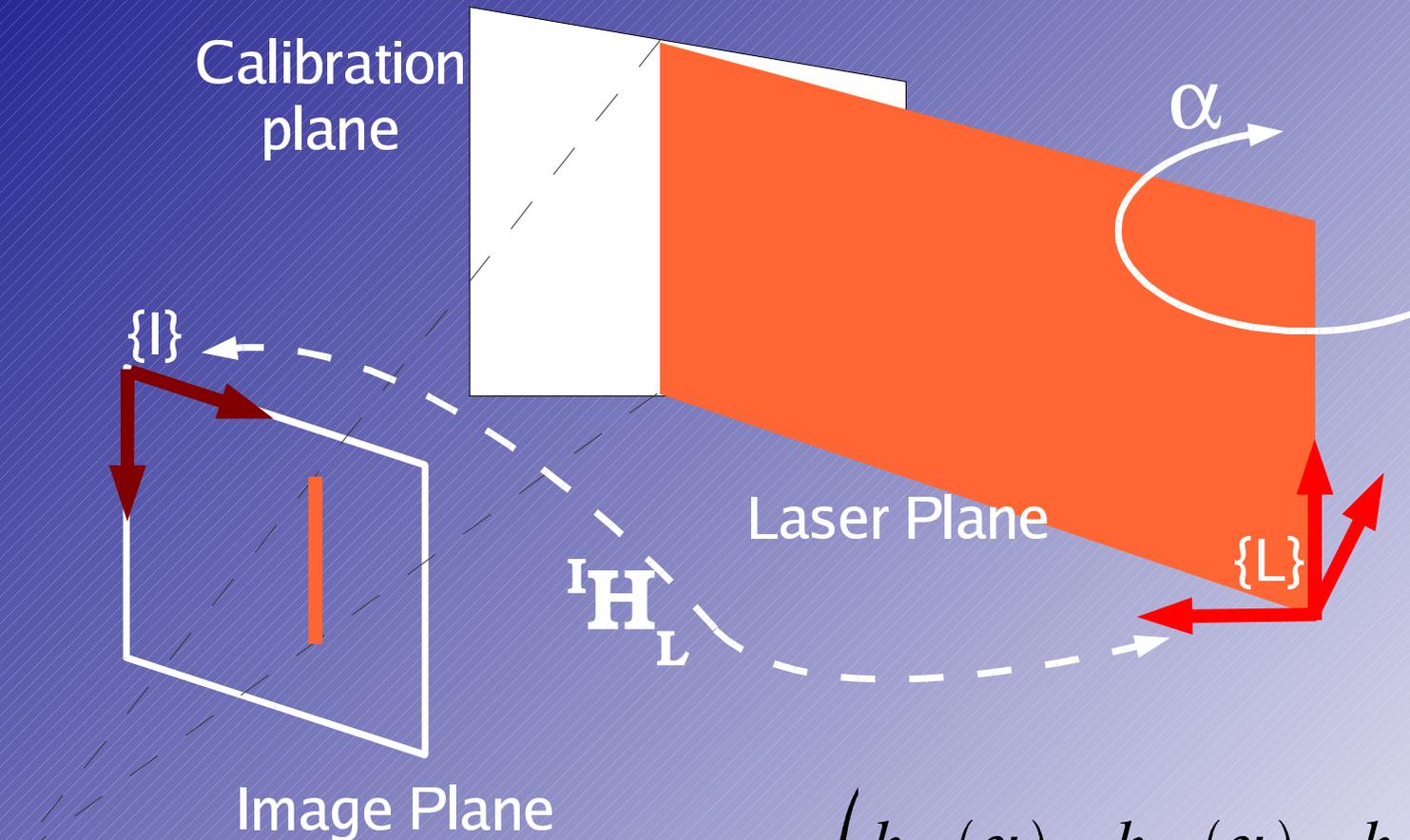


***Realistic  
Animation***

# Accuracy (Peak detection)

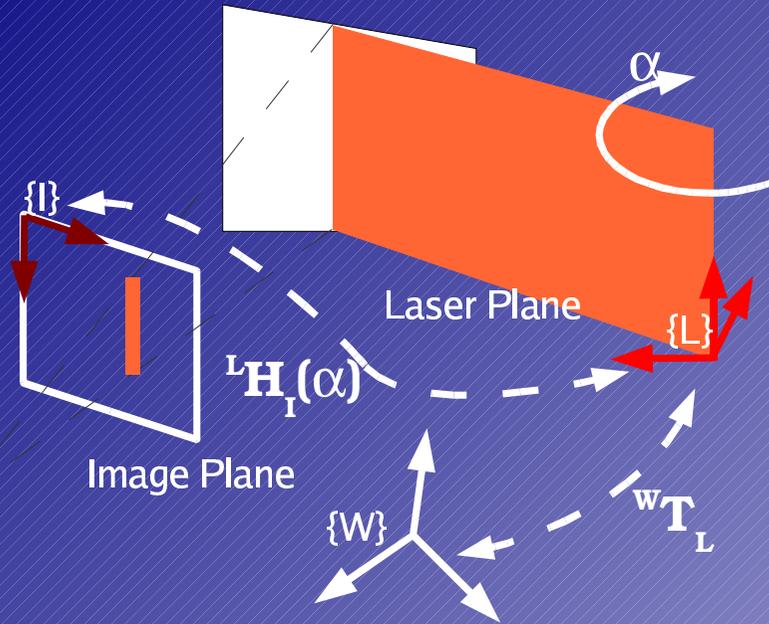


# Projective Calibration (I)



$${}^I H_L(\alpha) = \begin{pmatrix} h_{11}(\alpha) & h_{12}(\alpha) & h_{13}(\alpha) \\ h_{21}(\alpha) & h_{22}(\alpha) & h_{23}(\alpha) \\ h_{31}(\alpha) & h_{32}(\alpha) & 1 \end{pmatrix}$$

# Projective Calibration (II)

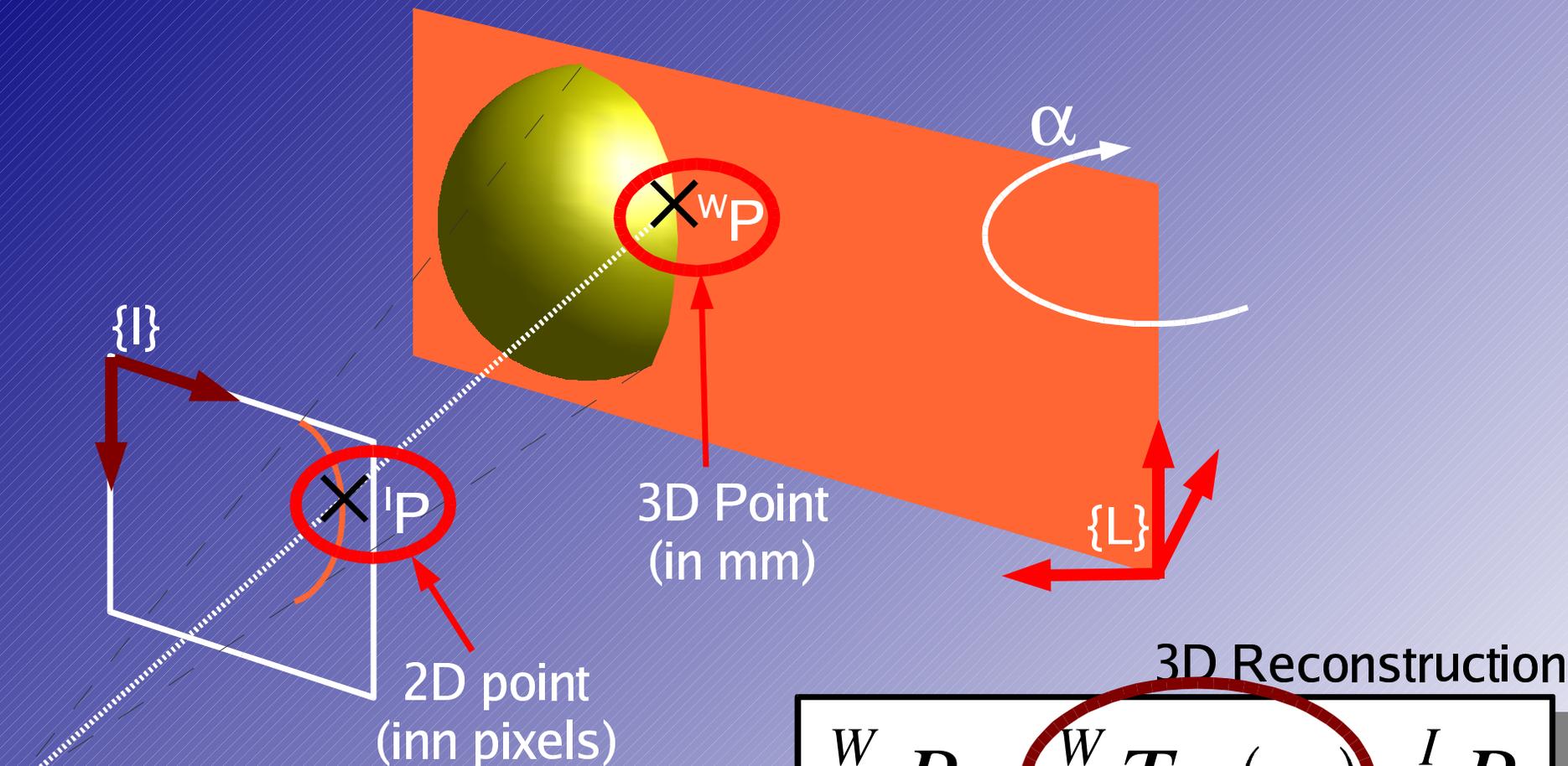


$${}^L H_I(\alpha) = \begin{pmatrix} h_{11}(\alpha) & h_{12}(\alpha) & h_{13}(\alpha) \\ h_{21}(\alpha) & h_{22}(\alpha) & h_{23}(\alpha) \\ h_{31}(\alpha) & h_{32}(\alpha) & 1 \end{pmatrix}$$

$${}^W T_L = \begin{pmatrix} t_{11} & t_{12} & t_{13} & t_{14} \\ t_{21} & t_{22} & t_{23} & t_{24} \\ t_{31} & t_{32} & t_{33} & 1 \end{pmatrix}$$

$${}^W T_I(\alpha) = {}^W T_L \cdot {}^L H_I(\alpha) = \begin{pmatrix} d_{11}(\alpha) & d_{12}(\alpha) & d_{13}(\alpha) \\ d_{21}(\alpha) & d_{22}(\alpha) & d_{23}(\alpha) \\ d_{31}(\alpha) & d_{32}(\alpha) & d_{33}(\alpha) \\ d_{41}(\alpha) & d_{42}(\alpha) & 1 \end{pmatrix}$$

# Projective Calibration (III)



$${}^W P = {}^W T_I(\alpha) \cdot {}^I P$$

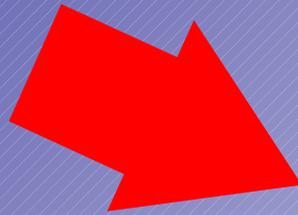
# Projective Calibration (IV)

3D Reconstruction

$${}^W P = {}^W T_I(\alpha) \cdot {}^I P$$

## Pros

- Easy calibration process
- Reconstruction by matrix multiplication
- $\alpha$  is the only dependence
- Noise robustness
- No precision mechanics needed for camera-laser alignment



**Very Fast 3D acquisition**

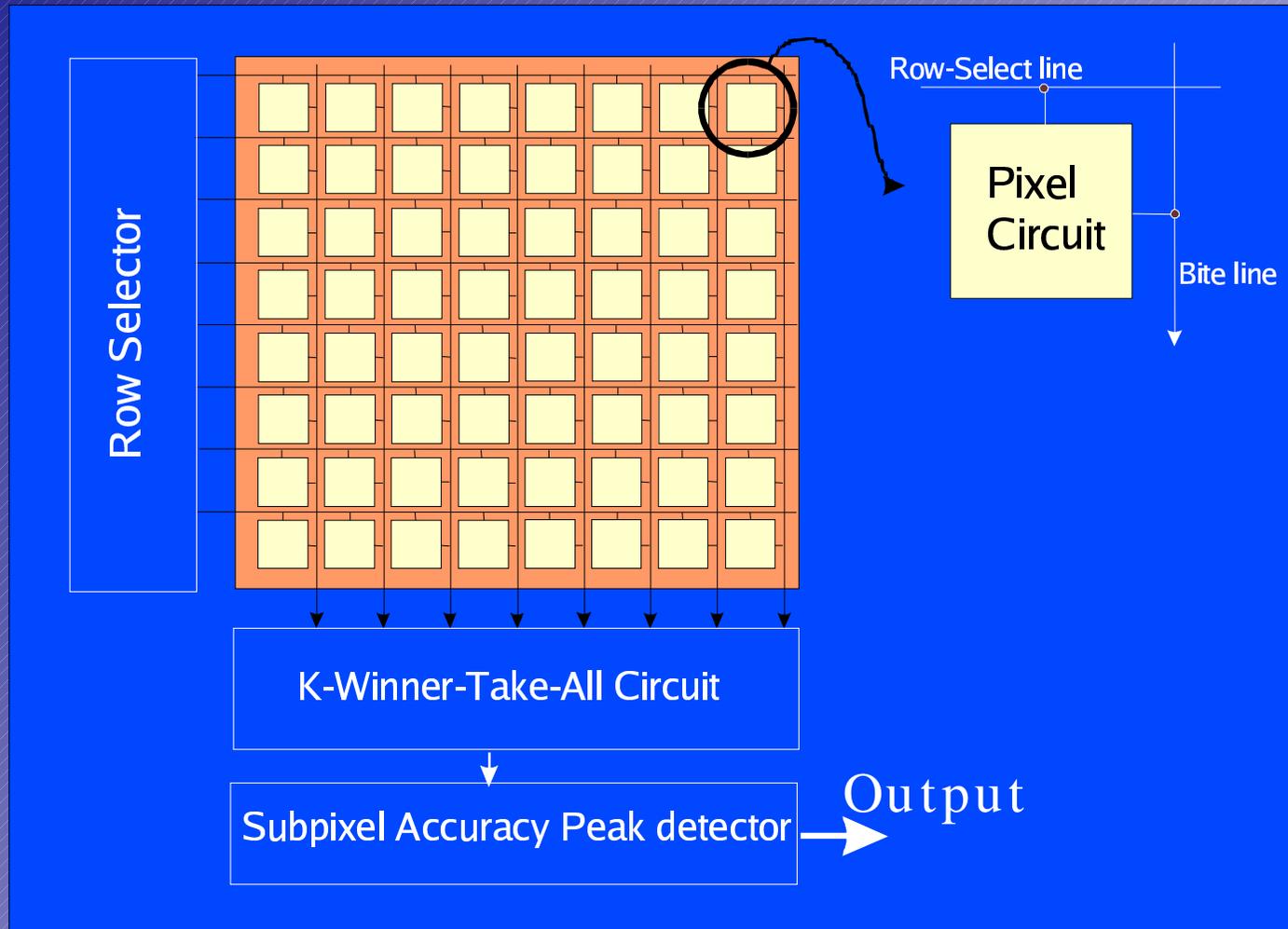
**High accuracy**

**Low cost mechanics**

# THE 3-DIMENSIONAL CAMERA

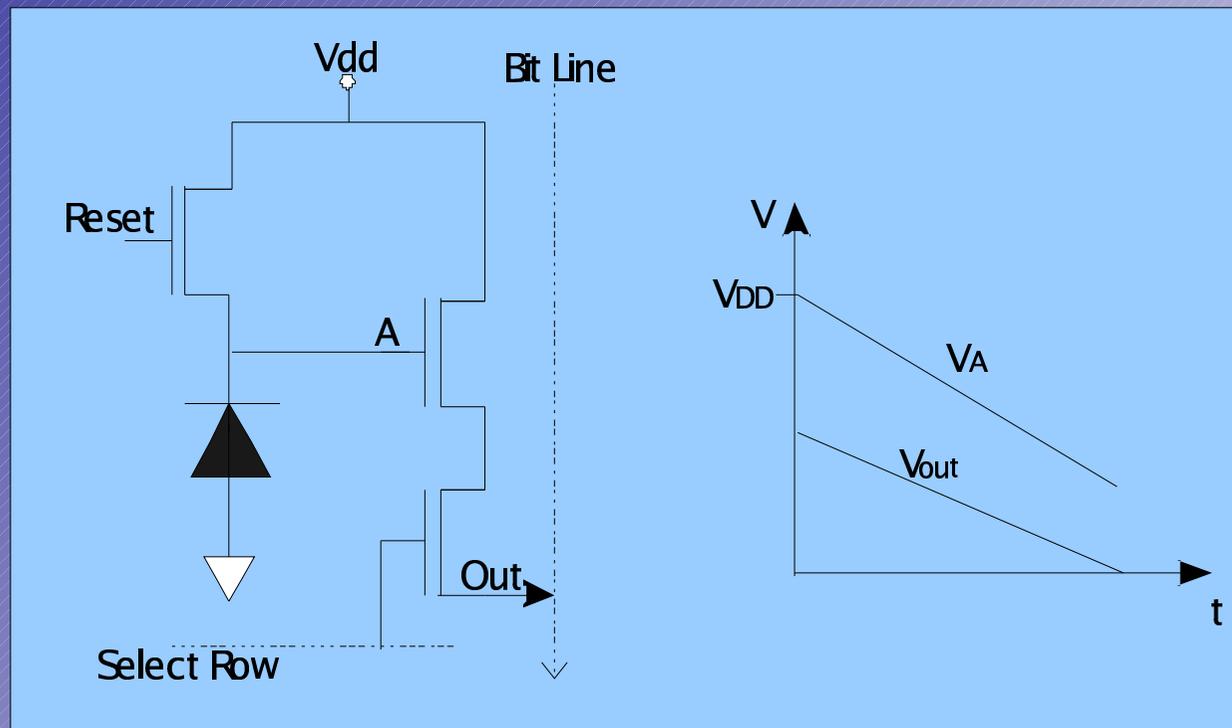
as a CMOS design approach

# CMOS Image Sensor Floorplan

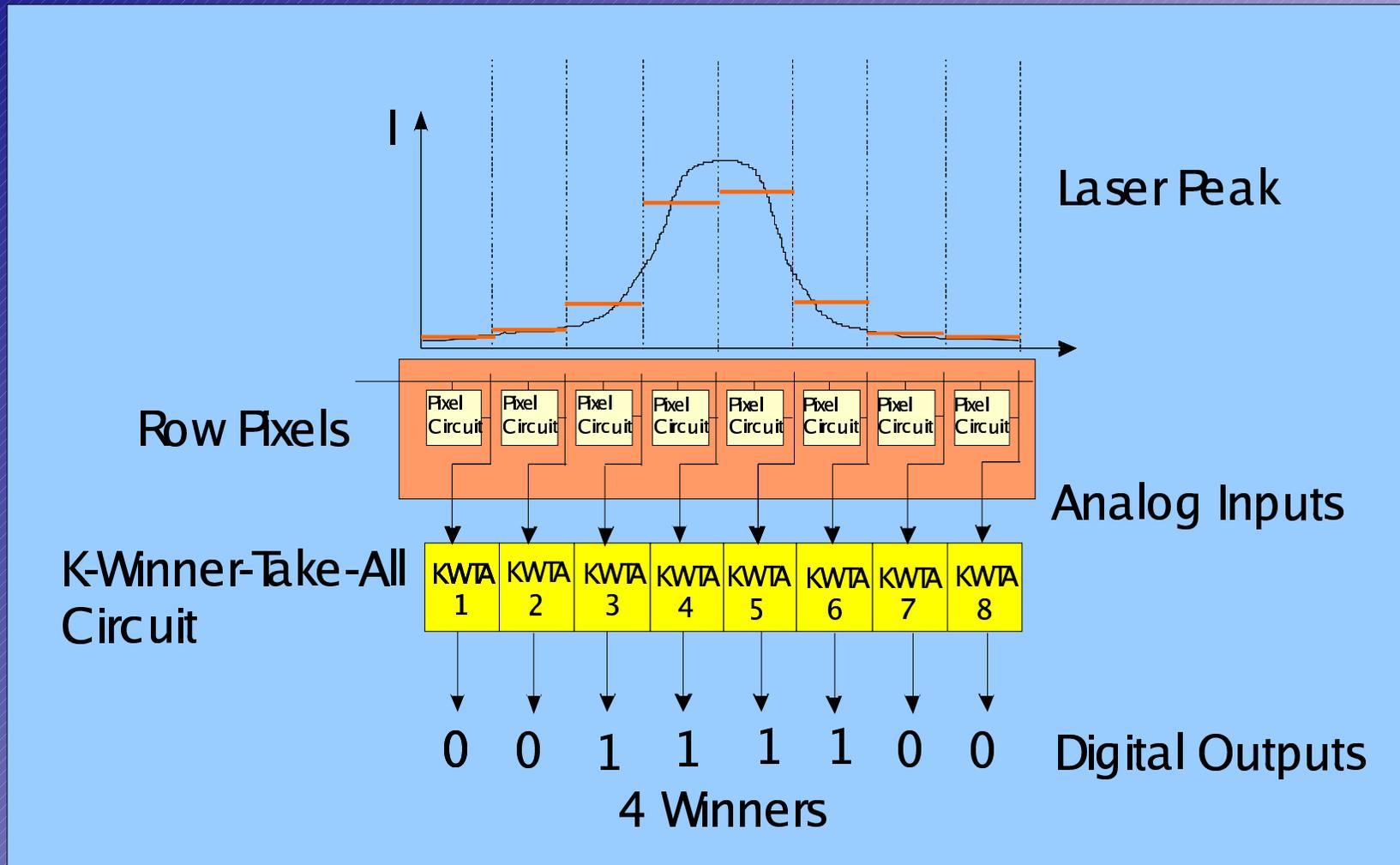


# Pixel Circuit

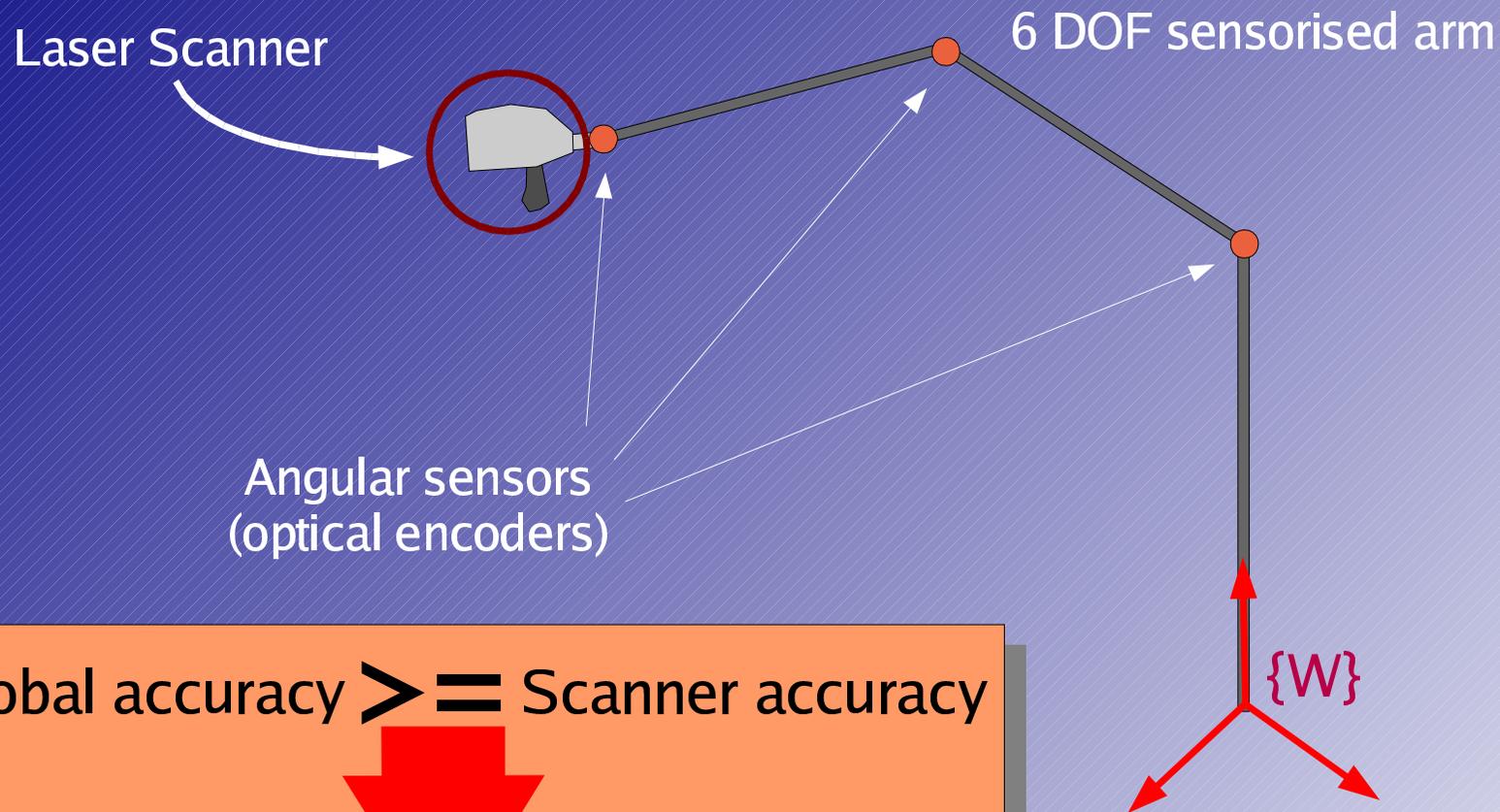
- APS(Active Pixel Sensor)
- Example:



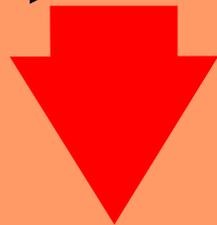
# K-Winner-Take-All Circuit



# Global Reconstruction (I)

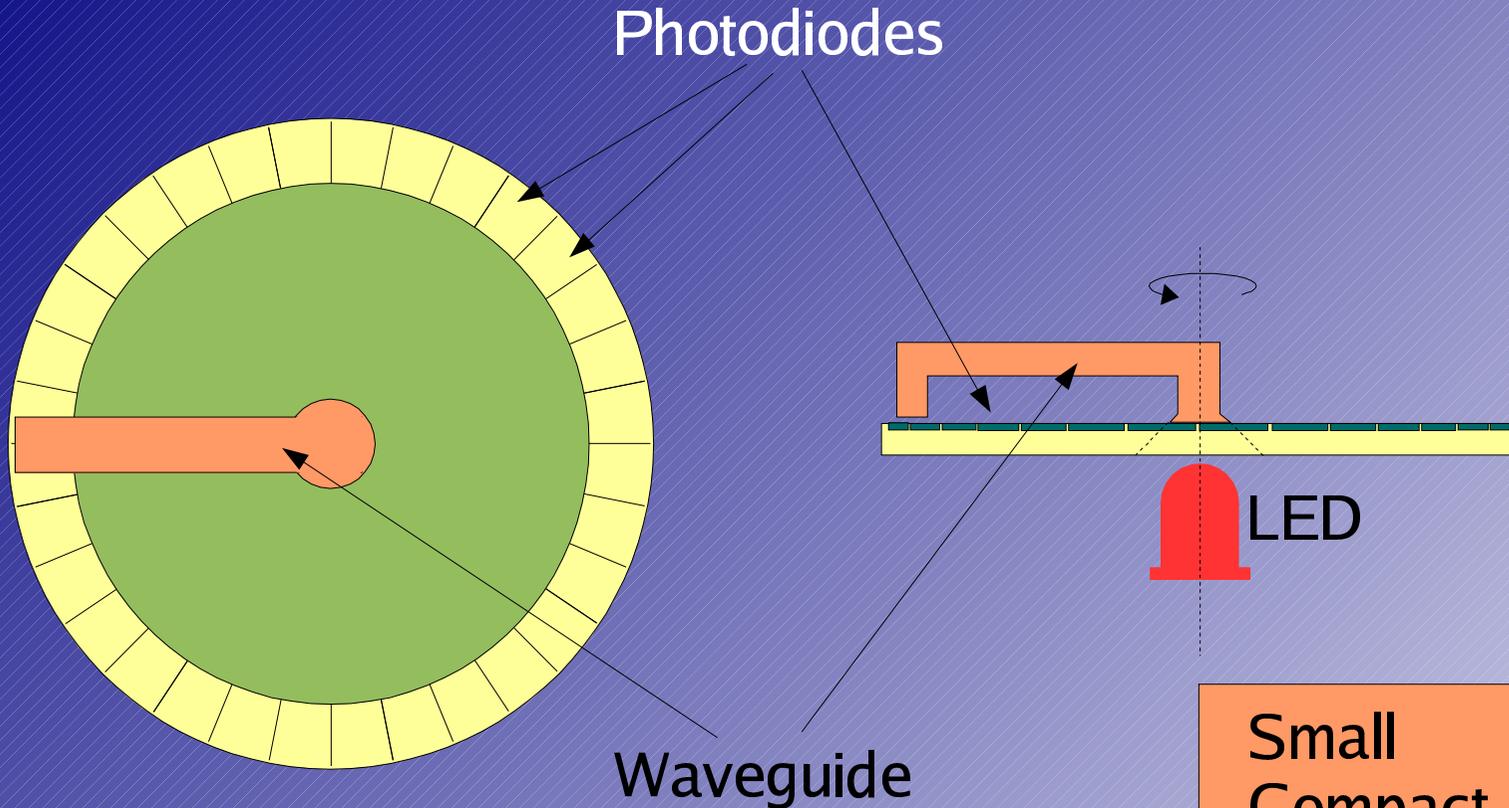


Global accuracy  $\geq$  Scanner accuracy

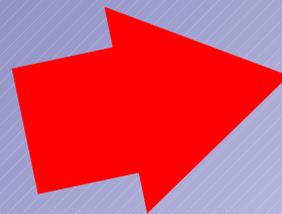


High resolution optical encoders

# Global Reconstruction (II)

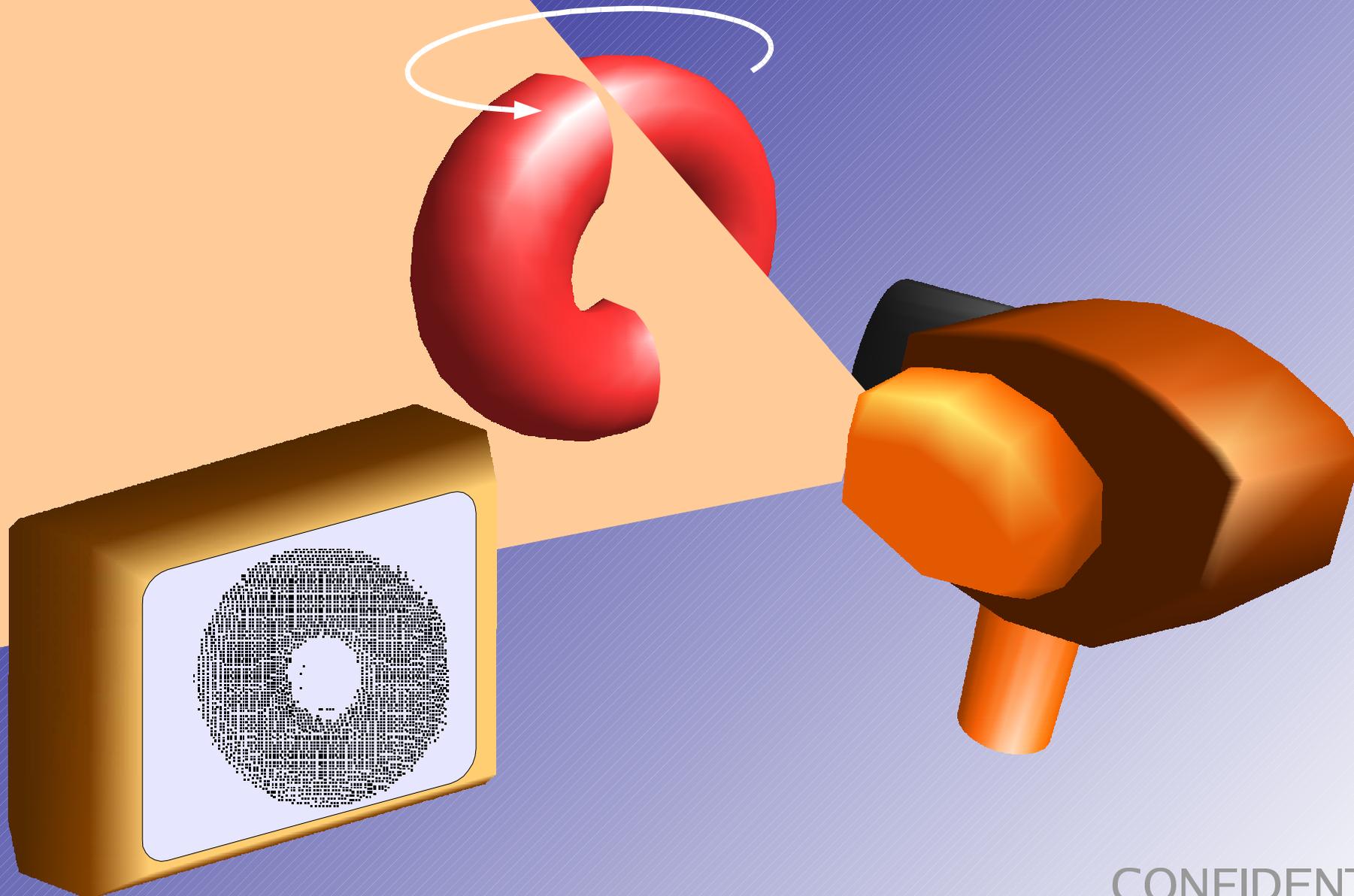


**Silicon angular sensor**



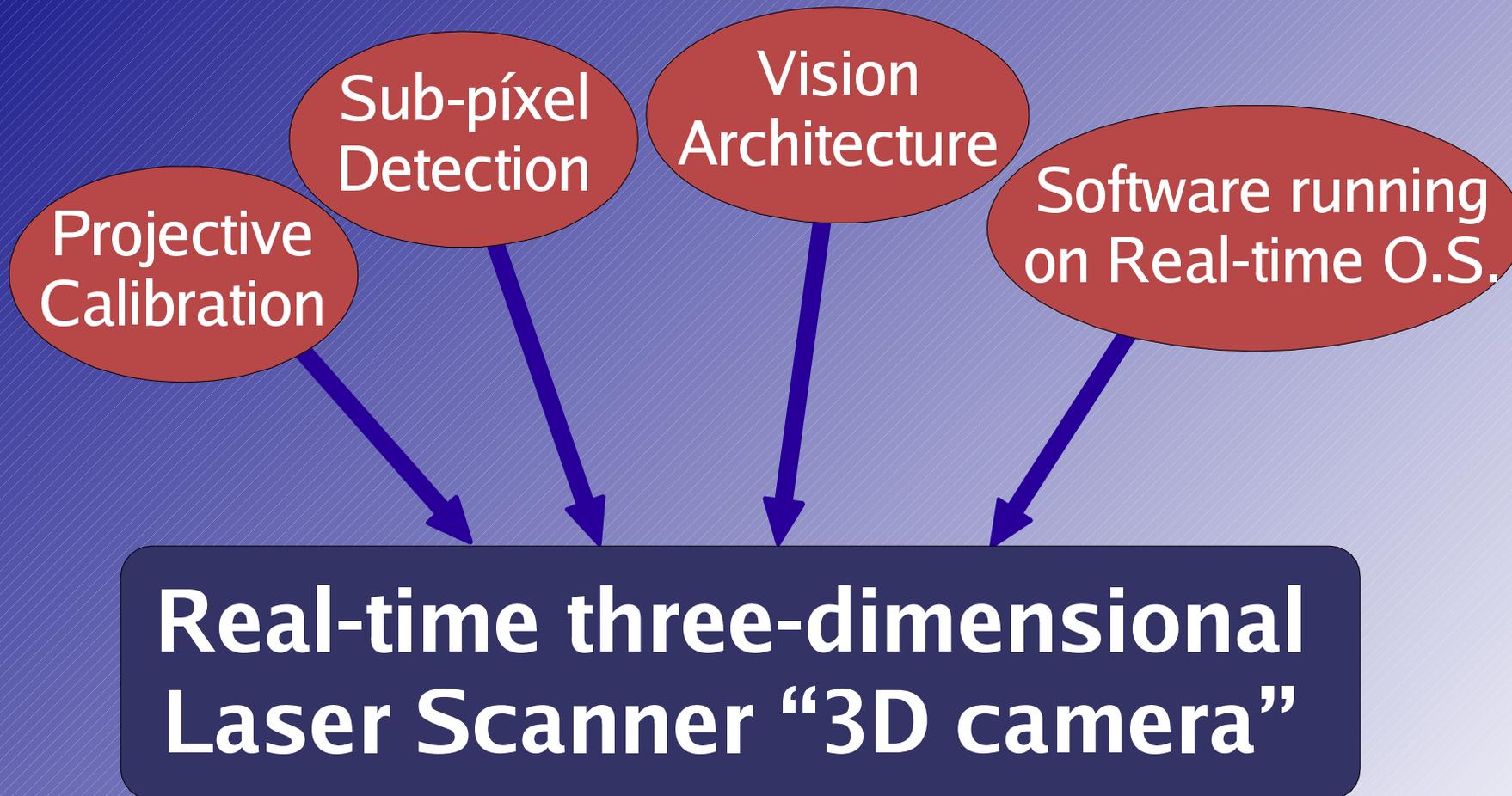
- Small
- Compact
- Rough
- Robust
- High Resolution
- Cheap

# ShapeSens: SPIN-OFF proposal



CONFIDENTIAL

# Product Idea



# Applications

## Industry

- Automotive
- Aerial
- Space
- Quality assurance
- Inverse engineering
- Rapid prototyping
- 3D modelling
- Automatic machine guidance

## Medicine

- Assisted surgery
- Dermatology
- Stetics

## Robotics

- 3D environment Perception
- 3D mapping
- Navigation

## Cinema

- Virtual scenery creation
- Realistic 3D graphic creation

## Virtual Reality

- Virtual worlds from Real worlds
- Augmented Reality

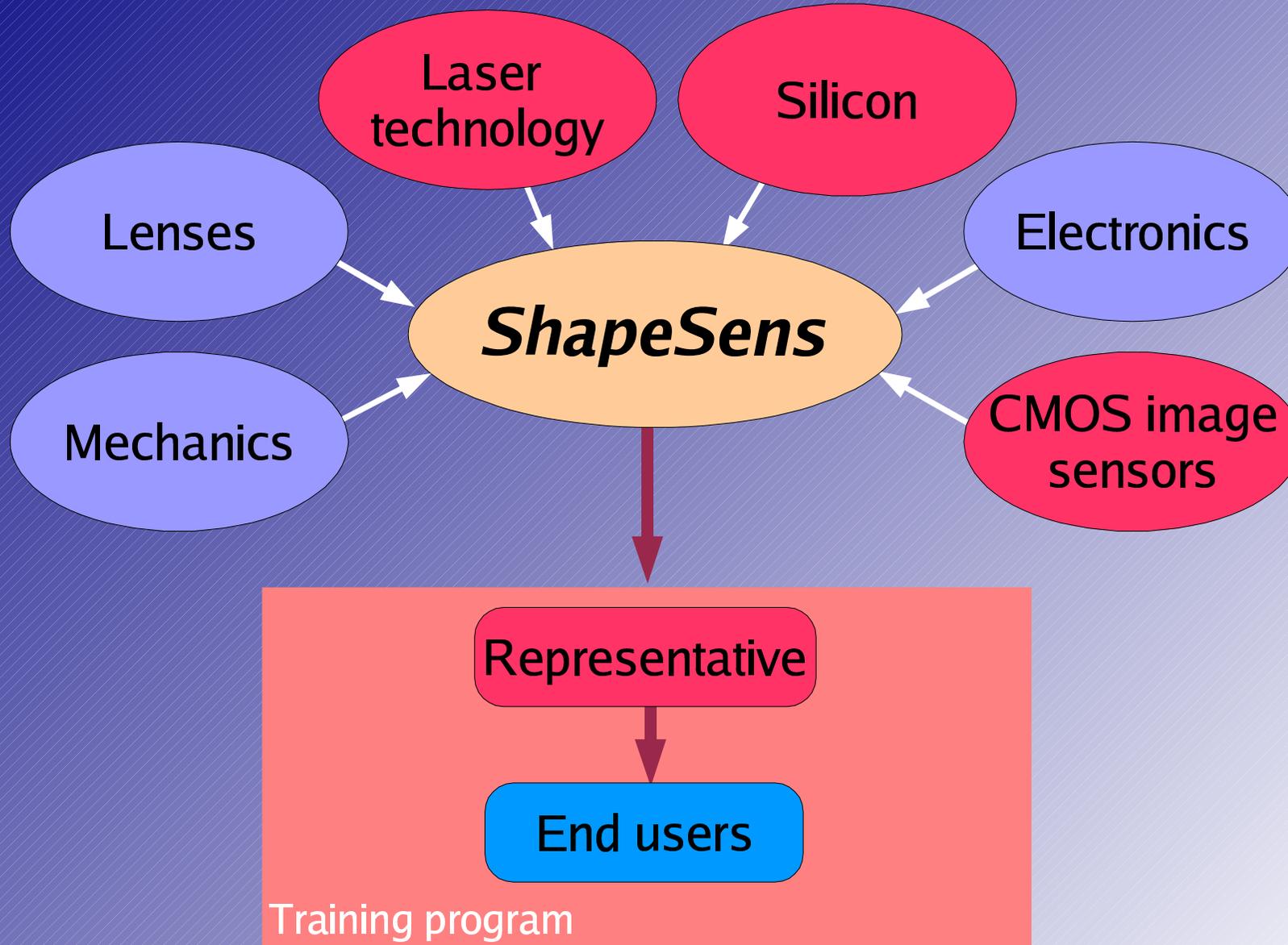
## Archaeology

- Digitisation of whole ruins for realistic virtual visits
- Ancient craftsman parts 3D reconstruction

## Art

- Artwork retorting

# Business plan



# Our Competitors

Manufacturer	Model	Accuracy(um)	Resolution	Speed(points/s)	3D data type
<b>INO</b>		250	256 points/perfil	230400	Profile
<b>MINOLTA</b>	Vivid 910	40	307000 points/frame	122800	Cloud of points
<b>3SHAPE</b>	H-100	10 a 100	100 a 700 um	3500	Profile
<b>KREON3D</b>		5		30000	Profile
<b>AXILA</b>	G-SCAN			16000	Profile
<b>HYMARC</b>		25		10000	Profile
<b>IVP</b>	M50		1536 Z values	15360000	Profile
<b>ORIGIN</b>	RS400	13	500 xy points		Cloud of points
<b>PERCEPTRON</b>	ScanWorks	50	420 um	23040	
<b>POLHEMUS</b>	FastScan Cobra	1000	500 um		Profile
<b>SURPHASER</b>	Model 25	25		200000	Cloud of points
<b>STEINBICHLER</b>	Comet T-Scan	30	150 um		Profile

# Performance of Our product

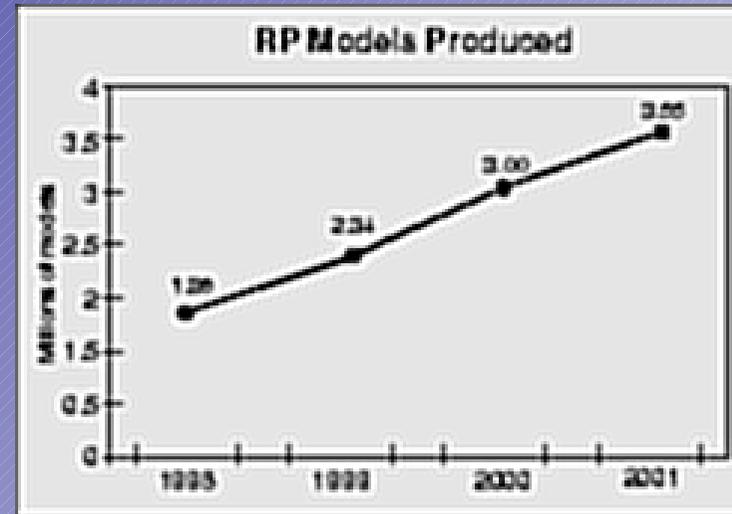
<b>Accuracy:</b>	<b>40 um</b>
<b>Resolution:</b>	<b>98 um</b>
<b>Speed*:</b>	<b>20000000 points/s</b>
<b>3D data type:</b>	<b>Cloud of points / Profile</b>

\* 30 clouds of points per second

# Expectations

## Rapid Prototyping: An example

RP users worldwide produced 3.55 million models and prototype parts in 2001. This is a growth of 18.3% from the 3 million produced in 2000\*.



**Almost any 3D industry (Hw or Sw) has experienced a significant growth, despite the decline in overall industry growth.**

\* Source: Wohlers Report 2002